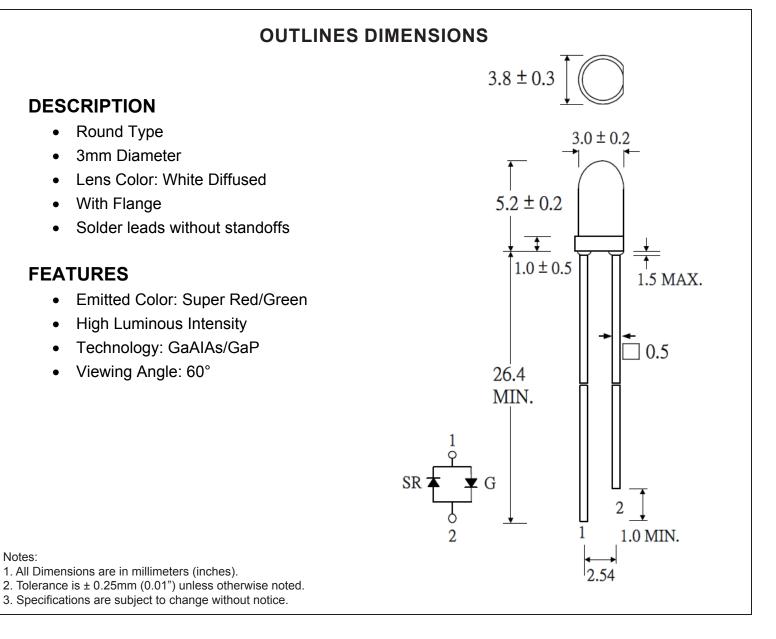


### SPECIFICATIONS

# CLB297RR1G1W



Part Number	Chip Material	Color of Emission	Lens Type	Viewing Angle	
CL297RR1G1W	AlGaAs/GaP	Red/Green	White Diffused	60°	





# **ABSOLUTE MAXIMUM RATINGS**

### (TA=25°C)

Parameter	Symbol	Max Rating	Unit			
Power Dissipation	PD	80	mW			
Pulse Current Forward Current	lfp	50	mA			
Reverse Voltage	VR	5	V			
Operating Temperature Range	Topr	-40~+85	°C			
Storage Temperature Range	Тѕтс	-40~+85	°C			
IFP = Pulse Width $\leq$ 10 ms, Duty Ratio $\leq$ 1/10. Soldering Condition: 260 °C/ 5sec						

# **OPTICAL-ELECTRICAL CHARACTERISTICS**

(TA=25°C)

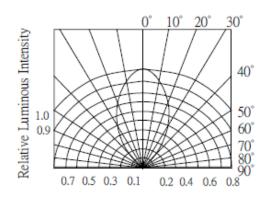
Parameter	Symbol	Test Condi- tion	Color	Value			Lipit
Parameter				Min	Тур	Max	Unit
Luminous Intensity	Iv	I⊧ = 20mA	Red	-	25	-	mcd
Luminous Intensity			Green	-	8	-	
	VF	I⊧ = 20mA	Red	-	1.9	2.4	V
Forward Voltage			Green	-	2.1	2.6	
Deverse Leekage Current	IR	V <sub>R</sub> = 5V	Red	-	-	10	μA
Reverse Leakage Current			Green	-	-	10	
	201/2	I⊧ = 20mA	Red	-	60	-	deg
Viewing Angle			Green	-	60	-	
Dominant Wayalangth	λD	l⊧ = 20mA	Red	-	645	-	nm
Dominant Wavelength			Green	-	570	-	
Peak Wavelength	λp	I⊧ = 20mA	Red	-	660	-	nm
reak wavelength			Green	-	568	-	

\*Tolerance of viewing angle: -10 / +5 deg.

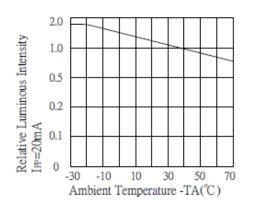




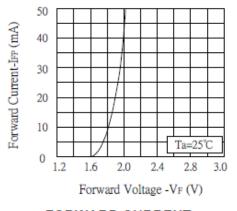
## **OPTICAL CHARACTERISTIC CURVES (RED)**



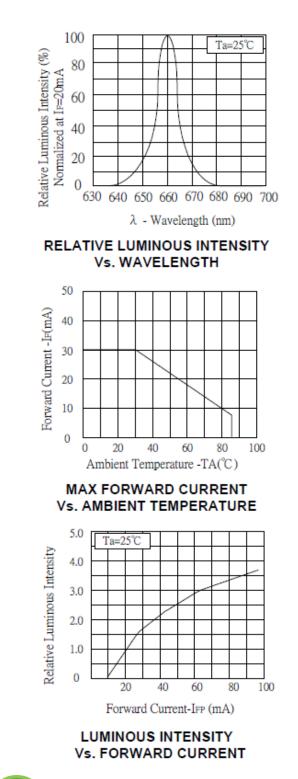
#### RADIATION DIAGRAM



LUMINOUS INTENSITY Vs. AMBIENT TEMPERATURE



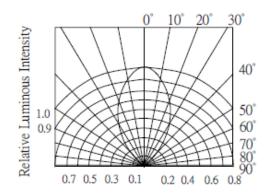
FORWARD CURRENT Vs. FORWARD VOLTAGE



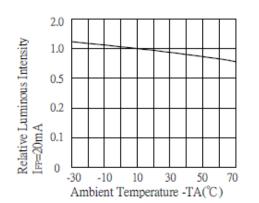




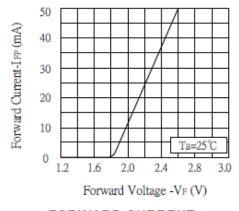
## **OPTICAL CHARACTERISTIC CURVES (GREEN)**



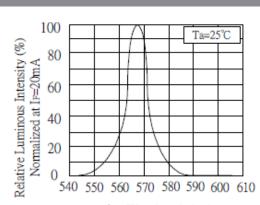
#### RADIATION DIAGRAM



#### LUMINOUS INTENSITY Vs. AMBIENT TEMPERATURE

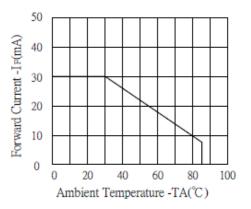


FORWARD CURRENT Vs. FORWARD VOLTAGE

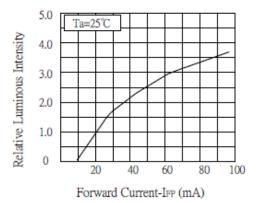


λ - Wavelength (nm)

#### RELATIVE LUMINOUS INTENSITY Vs. WAVELENGTH



MAX FORWARD CURRENT Vs. AMBIENT TEMPERATURE



#### LUMINOUS INTENSITY Vs. FORWARD CURRENT





## SOLDERING CONDITIONS – LAMP TYPE LED

### **SOLDERING CONDITION (Pb-Free)**

- Iron: Soldering Iron: 30W Max Temperature 350 °C Max Soldering Time: 3 Seconds Max (one time) Distance: 2mm Min (from solder joint to body)
- Wave soldering Profile: Dip Soldering Preheat: 120 °C Max Preheat time: 60 seconds Max Ramp-Up 2 °C/sec (Max) Ramp-Down: -5 °C/sec (max) Solder Bath: 260 °C Max Dipping Time: 3 seconds max Distance: 2mm Min (from solder joint to body)

